

# ALPHA<sup>®</sup> EF-8000

Low Rosin, Pb-Free/Sn-Pb Capable Wave Flux

## DESCRIPTION

**ALPHA EF-8000** is a rosin-containing flux designed to provide the attributes of excellent solderability and reliability in general and high-density boards in both Lead-Free and eutectic tin/lead processes. It is designed to have low bridging on bottom side QFP's with 144-168 leads as well as superior performance in hole fill and solderballing. Additionally, it provides good lead free solder joint cosmetics with an evenly spread, tack free residue.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

## FEATURES & BENEFITS

### Features for Pb-Free

- Good hole-fill demonstrated by >96% yield on 10 mil holes.
- Low bridging performance on connectors.
- Good micro-solder ball performance in Lead-Free applications
- Pin testable

### Benefits

- Excellent Lead-Free soldering performance on various board finishes.
- Evenly spread, tack free residue.
- Capable for high density as well as general purpose Lead-Free soldering processes.
- Can be used in Pb free or Sn/Pb processes

## APPLICATION

**PREPARATION:** In order to maintain consistent soldering performance and electrical reliability, it is important to begin the process with circuit boards and components that meet established requirements for solderability and ionic cleanliness. It is suggested that assemblers establish specifications on these items with their suppliers and that suppliers provide Certificates of Analysis with shipments and/or assemblers perform incoming inspection. A common specification for the ionic cleanliness of incoming boards and components is 5µg/in<sup>2</sup> maximum, as measured by an Omegameter with heated solution.

Care should be taken in handling the circuit boards throughout the process. Boards should always be held at the edges. The use of clean, lint-free gloves is also recommended.

Conveyors, fingers and pallets should be cleaned. Alpha brand stencil cleaner is recommended for this process.

**FLUX APPLICATION:** ALPHA EF-8000 can be applied by spray or foam. When spray fluxing, the uniformity of the coating can be visually checked by running a piece of cardboard over the spray fluxer or by processing a board-sized piece of tempered glass through the spray and then through the preheat section.

| Operating Parameter  | Recommendation for Sac 305  | Recommendation for 63/37 Sn/Pb   |
|--|---|--|
| Amount of Flux Applied   | Spray: 1200 to 1600µg/in <sup>2</sup> of solids/in <sup>2</sup> for dual wave and 1000 to 1200 µg/in <sup>2</sup> of solids/in <sup>2</sup> for single wave soldering                                       | Spray: 1000 to 1200µg/in <sup>2</sup> of solids/in <sup>2</sup> for dual wave and 600 to 900µg/in <sup>2</sup> of solids/in <sup>2</sup> for single wave soldering |
| Top-Side Preheat Temperature   | 80 to 110 °C  | 75 to 95 °C  |
| Bottom side Preheat Temperature  | 0 to +40 °F (0 to +22 °C) vs. Top-Side  | 0 to +40 °F (0 to +22 °C) vs. Top-Side   |
| Recommended Preheat Profile  | Straight ramp to desired top-side temperature   | Straight ramp to desired top-side temperature  |
| Maximum Ramp Rate of Topside Temperature<br>(to avoid component damage)  | 2 °C/second (3.5 °F/second) maximum   | 2 °C/second (3.5 °F/second) maximum  |
| Conveyor Angle   | 5 to 8° (6° most common recommended by equipment manufacturers)   | 5 to 8° (6° most common recommended by equipment manufacturers)  |
| Conveyor Speed   | 1.5 to 2.0 meters/minute for single wave, 1.8 to 2.2 meters/minute for dual wave. EF-8000 is capable of running at a slower conveyor speed to accommodate certain types of Lead Free wave soldering process | 1.5 to 2.0 meters/minute for single wave, 1.8 to 2.2 meters/minute for dual wave   |
| Contact Time in the Solder (includes Chip Wave and Primary Wave)   | 1.5 to 4.0 seconds (2½ to 3 seconds most common)  | 1.5 to 4.0 seconds (2½ to 3 seconds most common)   |
| Solder Pot Temperature:  | 255 to 265 °C   | 240 to 250 °C  |
| <p><i>These are general guidelines which have proven to yield excellent results; however, depending upon your equipment, components, and circuit boards, your optimal settings may be different. In order to optimize your process, it is recommended to perform a design experiment, optimizing the most important variables (amount of flux applied, conveyor speed, topside preheat temperature, solder pot temperature and board orientation).</i></p> |   |  |

**FLUX SOLIDS CONTROL:** If rotary drum spray fluxing, the flux solids will need to be controlled via thinner addition. For measuring the solids content, Alpha's Flux Solids Control Kit #3, a digital titrator, is suggested. Request Alpha's Technical Bulletin SM-458 for details on the kit and titration procedure. When operating a rotary drum fluxer continuously, the acid number should be checked every eight hours. Over time, debris and contaminants will accumulate in recirculating type flux applicators. For consistent soldering performance, dispose of spent flux every 40 hours of operation. After emptying the flux, the reservoir should be thoroughly cleaned with IPA.

**RESIDUE REMOVAL:** ALPHA EF-8000 is a no-clean flux and the residues are designed to be left on the board. If desired, flux residues can be removed with ALPHA 2110 saponifier cleaner and with other commercially available solvent cleaners and saponifier cleaners.

#### TECHNICAL DATA

| Item                                | Typical Values               | Item                              | Typical Values |
|-------------------------------------|------------------------------|-----------------------------------|----------------|
| Appearance                          | Clear,<br>Light Amber Liquid | pH, 5% v/v aqueous<br>solution    | 3.1            |
| Solids Content, wt/wt               | 6.0                          | Recommended<br>Thinner            | ALPHA 425      |
| Specific Gravity @<br>25 °C (77 °C) | 0.807± 0.003                 | Shelf Life (from Date<br>of Mfg.) | 360 days       |
| Acid Number (mg KOH/g)              | 27.0 ± 1.5                   | IPC J-STD-004<br>Designation      | ROL0           |
| Flash Point (T.C.C.)                | 17°C                         |                                   |                |

#### CORROSION & ELECTRICAL TESTING

##### CORROSION TESTING

| Test  | Requirement for ROL0             | Results                     |
|---|----------------------------------|-----------------------------|
| Silver Chromate Paper<br>IPC-TM 650 Test Method 2.3.33  | No detection of halide           | PASS                        |
| Copper Mirror Tests<br>IPC-TM 650 Test Method 2.6.32    | No complete removal of<br>copper | PASS                        |
| Copper Corrosion Test<br>IPC-TM 650 Test Method 2..3.15 | No evidence of corrosion         | No Evidence of<br>Corrosion |

**J-STD-004 SURFACE INSULATION RESISTANCE**

| Test   | Conditions          | Requirements               | Results                     |
|--|---------------------|----------------------------|-----------------------------|
| "Comb-Down"<br>Un-cleaned  | 85°C/85% RH, 7 days | $> 1.0 \times 10^8 \Omega$ | $1.0 \times 10^9 \Omega$    |
| "Comb-Up" Un-<br>cleaned   | 85°C/85% RH, 7 days | $> 1.0 \times 10^8 \Omega$ | $9.2 \times 10^{10} \Omega$ |
| Control Boards   | 85°C/85% RH, 7 days | $> 1.0 \times 10^9 \Omega$ | $8.3 \times 10^9 \Omega$    |
| IPC Test Condition (per J-STD-004A): -50V, measurement @ 100V/IPC B-24 board (0.4 mm lines, 0.5 mm spacing). |                     |                            |                             |

**JIS STANDARD SURFACE INSULATION RESISTANCE**

| Test   | Conditions            | Requirements                  | Controls                      | Results                     |
|--|-----------------------|-------------------------------|-------------------------------|-----------------------------|
| Initial  | Ambient               | $> 1.0 \times 10^{11} \Omega$ | $> 1.0 \times 10^{11} \Omega$ | $1.0 \times 10^{12} \Omega$ |
| After 7 days   | 40 °C / 90% RH        | $> 1.0 \times 10^{10} \Omega$ | $> 1.0 \times 10^{11} \Omega$ | $2.0 \times 10^{11} \Omega$ |
| Recovered  | 25 °C /75% RH, 7 days | $> 1.0 \times 10^{11} \Omega$ | $> 2.0 \times 10^{11} \Omega$ | $1.0 \times 10^{12} \Omega$ |
| All Measurements @ 100V, JIS Boards (0.32 mm lines, 0.32 mm spacing, same as IPC B25 Boards) |                       |                               |                               |                             |

**BELLCORE SURFACE INSULATION RESISTANCE**

| Test   | Conditions            | Requirements                  | Results                     |
|--|-----------------------|-------------------------------|-----------------------------|
| "Comb-Down"<br>Un-cleaned  | 35 °C /85% RH, 5 days | $> 1.0 \times 10^{11} \Omega$ | $3.9 \times 10^{11} \Omega$ |
| "Comb-Up"<br>Un-cleaned  | 35 °C /85% RH, 5 days | $> 1.0 \times 10^{11} \Omega$ | $2.5 \times 10^{11} \Omega$ |
| Control Boards   | 35 °C /85% RH, 5 days | $> 2.0 \times 10^{11} \Omega$ | $9.2 \times 10^{11} \Omega$ |
| Bellcore Test Condition (per GR 78-CORE, Issue 1: 48 Volts, measurement @ 100V/25 mil lines/50 mil spacing). |                       |                               |                             |

**BELLCORE ELECTROMIGRATION**

| Test   | SIR (Initial)               | SIR (Final)                 | Requirement                   | Result | Visual Result |
|--|-----------------------------|-----------------------------|-------------------------------|--------|---------------|
| "Comb-Up"<br>Un-cleaned  | $4.6 \times 10^{10} \Omega$ | $2.0 \times 10^{11} \Omega$ | SIR (Initial)/SIR (Final) <10 | PASS   | PASS          |
| "Comb-Down"<br>Uncleaned   | $2.4 \times 10^{10} \Omega$ | $7.4 \times 10^{10} \Omega$ | SIR (Initial)/SIR (Final) <10 | PASS   | PASS          |
| Bellcore Test Condition (per GR 78-CORE, Issue 1): 65 °C /85% RH/500 Hours/10V, measurement @ 100V/IPC B-25B Pattern (12.5 mil lines, 12.5 mil spacing). |                             |                             |                               |        |               |

**SAFETY & WARNING**

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use. **Safety Data Sheets are available at [MacdermidAlpha.com/assembly-solutions/knowledge-base](http://MacdermidAlpha.com/assembly-solutions/knowledge-base)**

**CONTACT INFORMATION**

To confirm this document is the most recent version, please contact  
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Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. **READ IT THOROUGHLY PRIOR TO PRODUCT USE.** Emergency safety directory assistance: US 1 202 464 2554, Europe + 44 1235 239 670, Asia + 65 3158 1074, Brazil 0800 707 7022 and 0800 172 020, Mexico 01800 002 1400 and (55) 5559 1588

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